

Title (en)  
METHOD FOR DISTRIBUTED SHIELDING AND/OR BYPASS FOR ELECTRONIC DEVICE WITH THREE-DIMENSIONAL INTERCONNECTION

Title (de)  
VERTEILTES ABSCHIRMUNGS- UND/ODER ENTKOPPLUNGSVERFAHREN FÜR VORRICHTUNG MIT DREIDIMENSIONALER VERDRAHTUNGSSTRUKTUR

Title (fr)  
PROCEDE DE BLINDAGE ET/OU DE DECOUPLAGE REPARTIS POUR UN DISPOSITIF ELECTRONIQUE A INTERCONNEXION EN TROIS DIMENSIONS

Publication  
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Application  
**EP 01956626 A 20010720**

Priority  
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Abstract (en)  
[origin: WO0209182A1] The invention concerns a method for distributed shielding and bypass for an electronic device with integrated components having three-dimensional interconnection, the inventive device and a method for making same. The device comprises, associated with each active component (2), at least a capacitor plane consisting of a thin foil (10) made of metal-coated dielectric material (11, 12) on its two planar surfaces. The components and capacitor planes are stacked and alternately assembled to form a block (1') whereof the side surfaces (21 to 24) bear conductors (13, 14) providing the three-dimensional interconnection. The metal coatings (11, 12) are delimited to be flush with the edges of the block only through tabs (110, 120). One of the metal coatings (11) connected to the ground acts as shield. The invention is particularly useful for producing very compact storage blocks.

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IPC 8 full level  
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